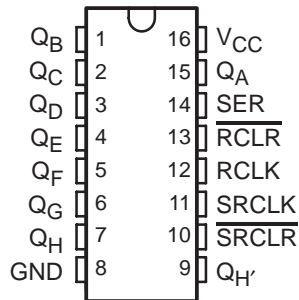


SN54HC594, SN74HC594 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

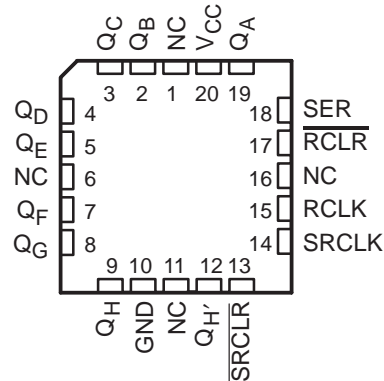
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- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 15$ ns
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- 8-Bit Serial-In, Parallel-Out Shift Registers With Storage
- Independent Direct Overriding Clears on Shift and Storage Registers
- Independent Clocks for Both Shift and Storage Registers

SN54HC594 . . . J OR W PACKAGE
SN74HC594 . . . D, DW, OR N PACKAGE
(TOP VIEW)



SN54HC594 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'HC594 devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. Separate clocks and direct overriding clear (\overline{RCLR} , \overline{SRCLR}) inputs are provided on both the shift and storage registers. A serial (Q_H) output is provided for cascading purposes.

Both the shift register (\overline{SRCLK}) and storage register (\overline{RCLK}) clocks are positive edge triggered. If both clocks are connected together, the shift register always is one count pulse ahead of the storage register.

The parallel (Q_A – Q_H) outputs have high-current capability. Q_H is a standard output.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HC594N	SN74HC594N
		Tube of 40	SN74HC594D	HC594
	SOIC – D	Reel of 2500	SN74HC594DR	
		Reel of 250	SN74HC594DT	
–55°C to 125°C	SOIC – DW	Tube of 40	SN74HC594DW	HC594
		Reel of 2000	SN74HC594DWR	
	CDIP – J	Tube of 25	SNJ54HC594J	SNJ54HC594J
	CFP – W	Tube of 150	SNJ54HC594W	SNJ54HC594W
	LCCC – FK	Tube of 55	SNJ54HC594FK	SNJ54HC594FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SN54HC594, SN74HC594

8-BIT SHIFT REGISTERS

WITH OUTPUT REGISTERS

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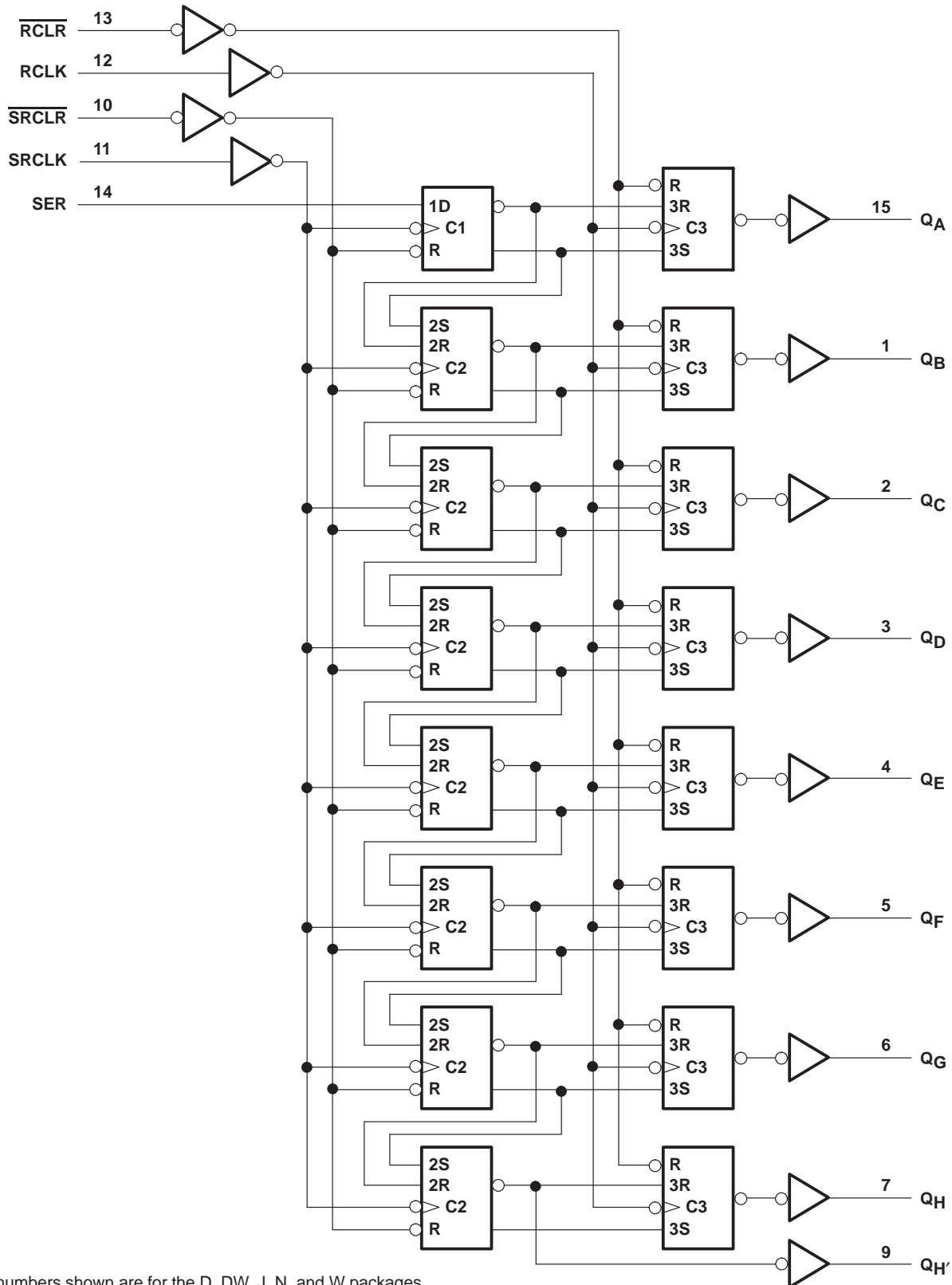
FUNCTION TABLE

INPUTS					FUNCTION
SER	SRCLK	$\overline{\text{SRCLR}}$	RCLK	$\overline{\text{RCLR}}$	
X	X	L	X	X	Shift register is cleared.
L	↑	H	X	X	First stage of shift register goes low. Other stages store the data of previous stage, respectively.
H	↑	H	X	X	First stage of shift register goes high. Other stages store the data of previous stage, respectively.
L	↓	H	X	X	Shift register state is not changed.
X	X	X	X	L	Storage register is cleared.
X	X	X	↑	H	Shift register data is stored in the storage register.
X	X	X	↓	H	Storage register state is not changed.

SN54HC594, SN74HC594 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

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logic diagram (positive logic)



Pin numbers shown are for the D, DW, J, N, and W packages.



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Supply voltage range, V_{CC}	−0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V_{CC} or GND	±70 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	73°C/W
DW package	57°C/W
N package	67°C/W
Storage temperature range, T_{stg}	−65°C to 150°C

NOTES:

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JEDEC 51-7.

SN54HC594, SN74HC594 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

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recommended operating conditions (see Note 3)

			SN54HC594			SN74HC594			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5			1.5			V
		V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 6 V	4.2			4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V			0.5			0.5	V
		V _{CC} = 4.5 V			1.35			1.35	
		V _{CC} = 6 V			1.8			1.8	
V _I	Input voltage		0		V _{CC}	0		V _{CC}	V
V _O	Output voltage		0		V _{CC}	0		V _{CC}	V
t _t	Input transition (rise and fall) time	V _{CC} = 2 V			1000			1000	ns
		V _{CC} = 4.5 V			500			500	
		V _{CC} = 6 V			400			400	
T _A	Operating free-air temperature		–55		125	–40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC594		SN74HC594		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998		1.9		1.9	V	
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		Q _{H'} , I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7		3.84		
				Q _A -Q _H , I _{OH} = -6 mA	3.98	4.3		3.7			3.84
		Q _{H'} , I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
				Q _A -Q _H , I _{OH} = -7.8 mA	5.48	5.8		5.2			5.34
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		Q _{H'} , I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
				Q _A -Q _H , I _{OL} = 6 mA		0.17	0.26		0.4		
		Q _{H'} , I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
				Q _A -Q _H , I _{OL} = 7.8 mA		0.15	0.26		0.4		
I _I	V _I = V _{CC} or 0		6 V		±0.1	±100		±1000		±1000	nA
I _{OZ}	V _O = V _{CC} or 0		6 V		±0.01	±0.5		±10		±5	μA
I _{CC}	V _I = V _{CC} or 0, I _O = 0		6 V			8		160		80	μA
C _i			2 V to 6 V		3	10		10		10	pF

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SN54HC594, SN74HC594

8-BIT SHIFT REGISTERS

WITH OUTPUT REGISTERS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25°C		SN54HC594		SN74HC594		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	2 V		5		3.3		4	MHz
		4.5 V		25		17		20	
		6 V		29		20		24	
t _w	SRCLK or RCLK high or low	2 V	100		150		125		ns
		4.5 V	20		30		25		
		6 V	17		25		21		
	SRCLR or RCLR low	2 V	100		150		125		
		4.5 V	20		30		25		
		6 V	17		25		21		
t _{su}	SER before SRCLK↑	2 V	90		135		110		ns
		4.5 V	18		27		22		
		6 V	15		23		19		
	SRCLK↑ before RCLK↑†	2 V	90		135		110		
		4.5 V	18		27		22		
		6 V	15		23		19		
	SRCLR low before RCLK↑	2 V	50		75		63		
		4.5 V	10		15		13		
		6 V	9		13		11		
	SRCLR high (inactive) before SRCLK↑	2 V	20		20		20		
		4.5 V	10		10		10		
		6 V	10		10		10		
	RCLR high (inactive) before SRCLK↑	2 V	5		5		5		
		4.5 V	5		5		5		
		6 V	5		5		5		
t _h	Hold time, SER after SRCLK↑	2 V		5		5		5	ns
		4.5 V		5		5		5	
		6 V		5		5		5	

† This setup time ensures that the output register receives stable data from the shift-register outputs. The clocks may be tied together, in which case the output register is one clock pulse behind the shift register.

SN54HC594, SN74HC594 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

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switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC594		SN74HC594		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{\max}			2 V	5	8		3.3		4		MHz
			4.5 V	25	35		17		20		
			6 V	29	40		20		24		
t_{pd}	SRCLK	Q_H'	2 V		50	150		225		185	ns
			4.5 V		20	30		45		37	
			6 V		15	25		38		31	
	RCLK	Q_A-Q_H	2 V		50	150		225		185	
			4.5 V		20	30		45		37	
			6 V		15	25		38		31	
t_{PHL}	$\overline{\text{SRCLR}}$	Q_H'	2 V		50	150		225		185	ns
			4.5 V		20	30		45		37	
			6 V		15	25		38		31	
	$\overline{\text{RCLR}}$	Q_A-Q_H	2 V		50	125		185		155	
			4.5 V		20	25		37		31	
			6 V		15	21		31		26	
t_t		Q_H'	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	
		Q_A-Q_H	2 V		38	60		90		75	
			4.5 V		8	12		18		15	
			6 V		6	10		15		13	

switching characteristics over recommended operating free-air temperature range, $C_L = 150$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC594		SN74HC594		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	RCLK	Q_A-Q_H	2 V		90	200		300		250	ns
			4.5 V		23	40		60		50	
			6 V		19	34		51		43	
t_{PHL}	$\overline{\text{RCLR}}$	Q_A-Q_H	2 V		90	200		300		250	ns
			4.5 V		23	40		60		50	
			6 V		19	34		51		43	
t_t		Q_A-Q_H	2 V		45	210		315		265	ns
			4.5 V		17	42		63		53	
			6 V		13	36		53		45	

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load	395	pF

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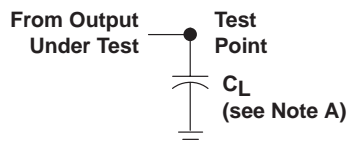


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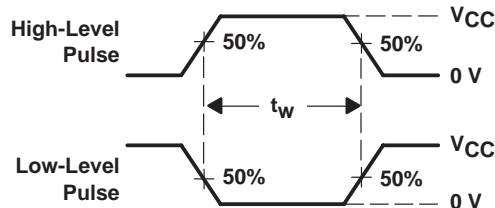
SN54HC594, SN74HC594 8-BIT SHIFT REGISTERS WITH OUTPUT REGISTERS

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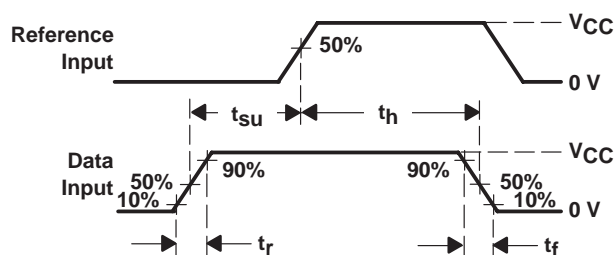
PARAMETER MEASUREMENT INFORMATION



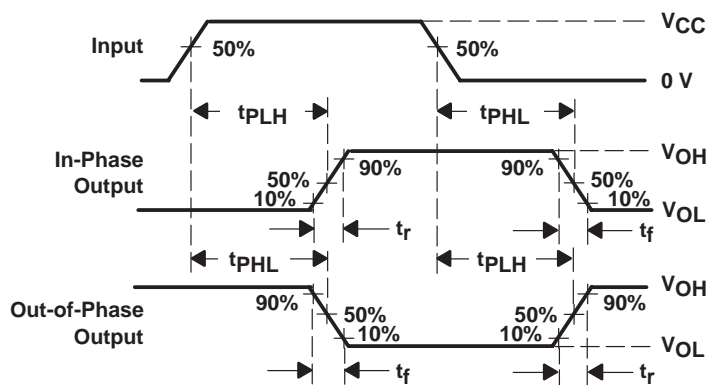
LOAD CIRCUIT



VOLTAGE WAVEFORMS
PULSE DURATIONS



VOLTAGE WAVEFORMS
SETUP AND HOLD AND INPUT RISE AND FALL TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

- NOTES: A. C_L includes probe and test-fixture capacitance.
B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r = 6$ ns, $t_f = 6$ ns.
C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
D. The outputs are measured one at a time with one input transition per measurement.
E. t_{PLH} and t_{PHL} are the same as t_{pd} .
F. t_f and t_r are the same as t_t .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC594D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DWE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DWRE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594DWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC594	Samples
SN74HC594N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC594N	Samples
SN74HC594NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC594N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC594DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC594DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
SN74HC594DWRG4	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



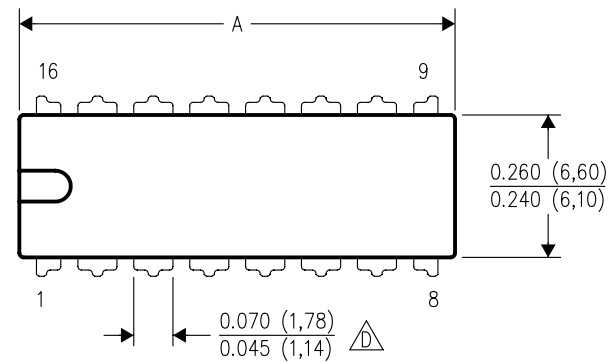
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC594DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC594DWR	SOIC	DW	16	2000	366.0	364.0	50.0
SN74HC594DWRG4	SOIC	DW	16	2000	367.0	367.0	38.0

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

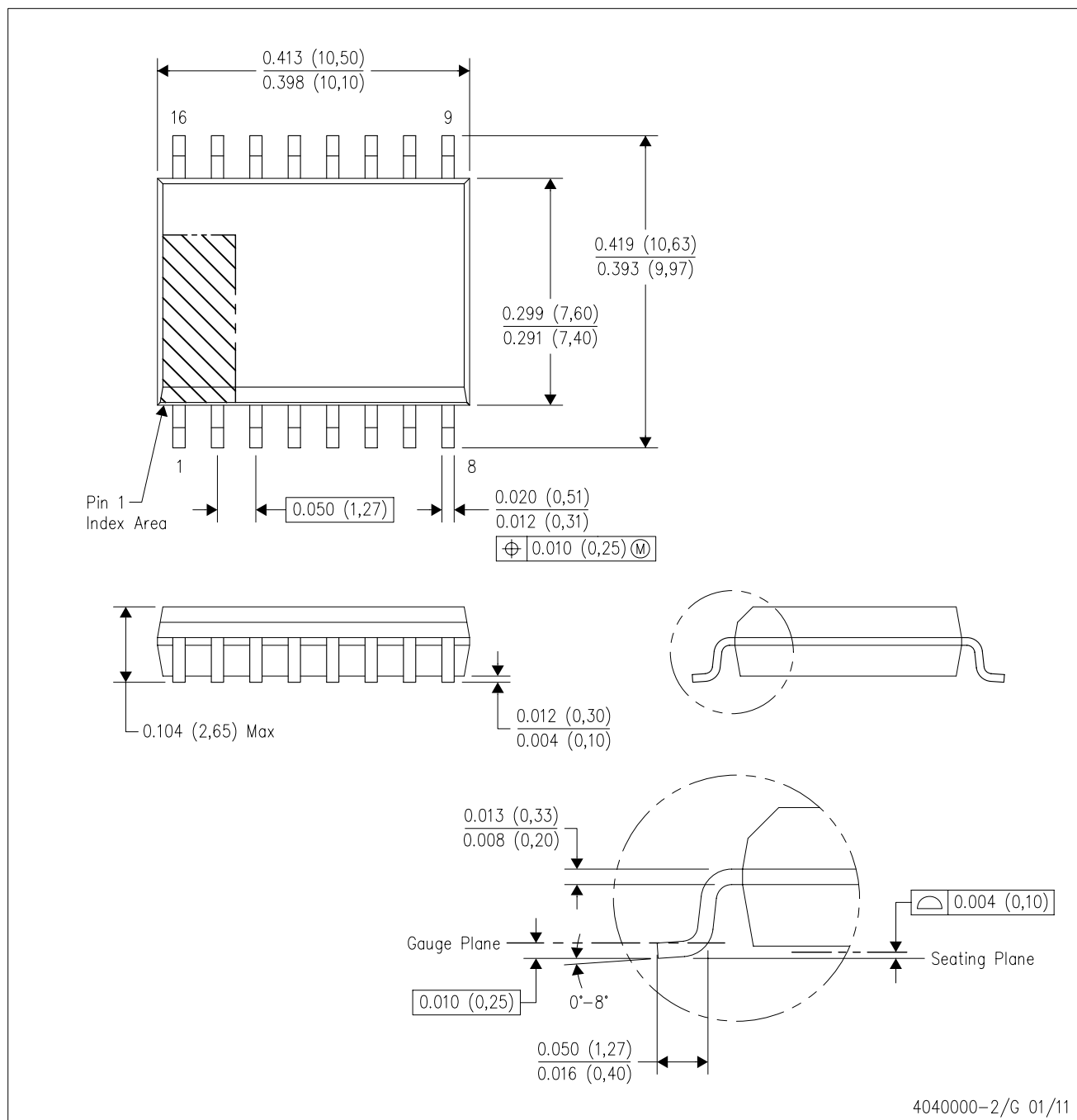
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R-PDSO-G16)

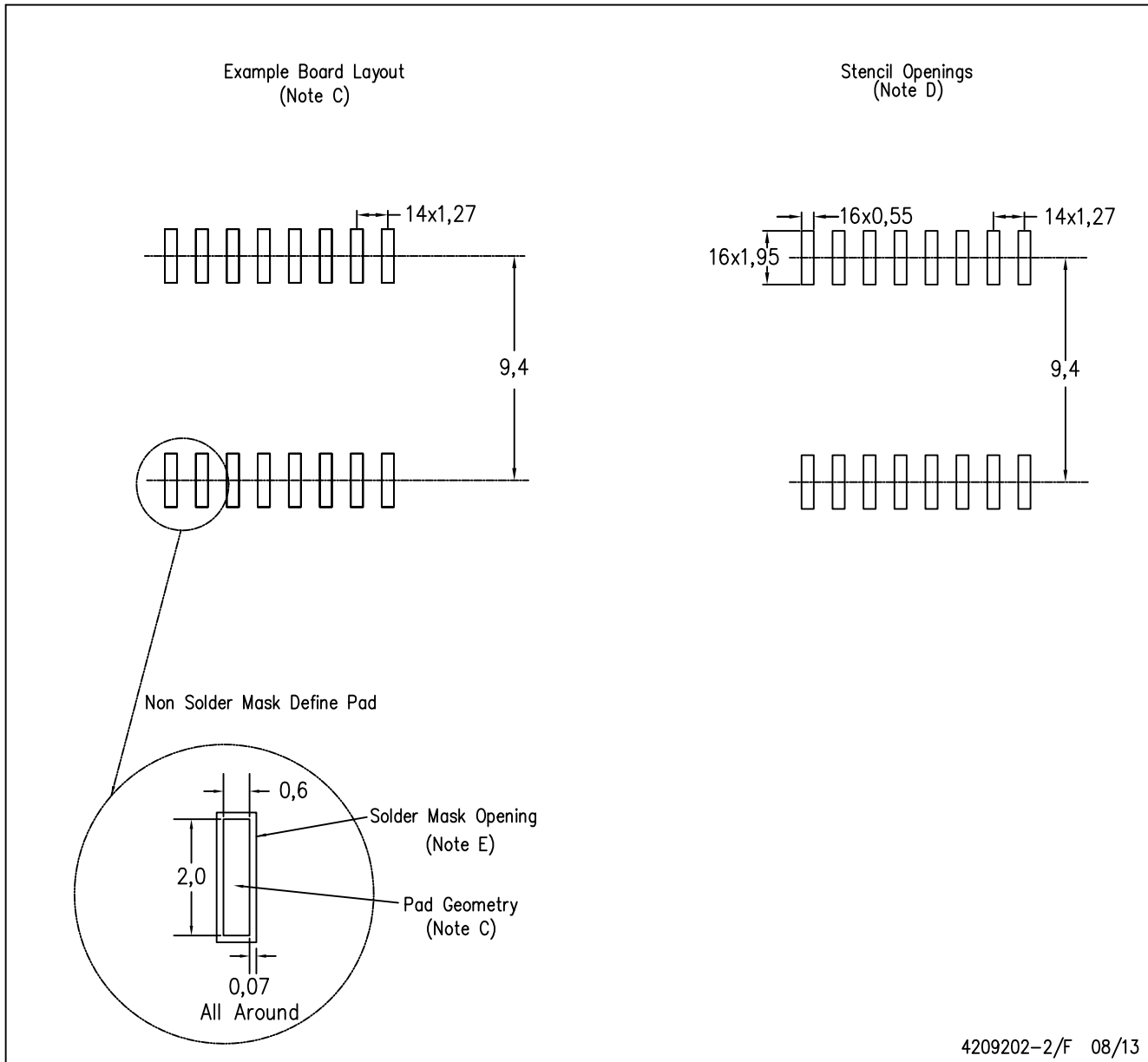
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-013 variation AA.

DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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